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**Field Device Integration (FDI®) –
Part 4: FDI Packages**

**Intégration des appareils de terrain (FDI®) –
Partie 4: Paquetages FDI**



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FIELD DEVICE INTEGRATION (FDI®) –

Part 4: FDI® Packages

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This third edition cancels and replaces the second edition published in 2021. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) added DocumentClass to Package Schema, Description of Feature Table and Documentation Catalog, individual schemas for Feature Table and Package Documentation Catalog, schema for UnitConversion, interactive download to device, and Feature Unit Conversion;
- b) moved DocumentClass to Package Documentation Catalog Schema;
- c) updated Description of Feature Table updated XML schema for Feature Table.

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Draft	Report on voting
65E/857/CDV	65E/914/RVC

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FIELD DEVICE INTEGRATION (FDI®) –

Part 4: FDI® Packages

1 Scope

This part of IEC 62769 specifies the FDI^{®1} Packages. The overall FDI[®] architecture is illustrated in Figure 1. The architectural components that are within the scope of this document have been highlighted in this figure.

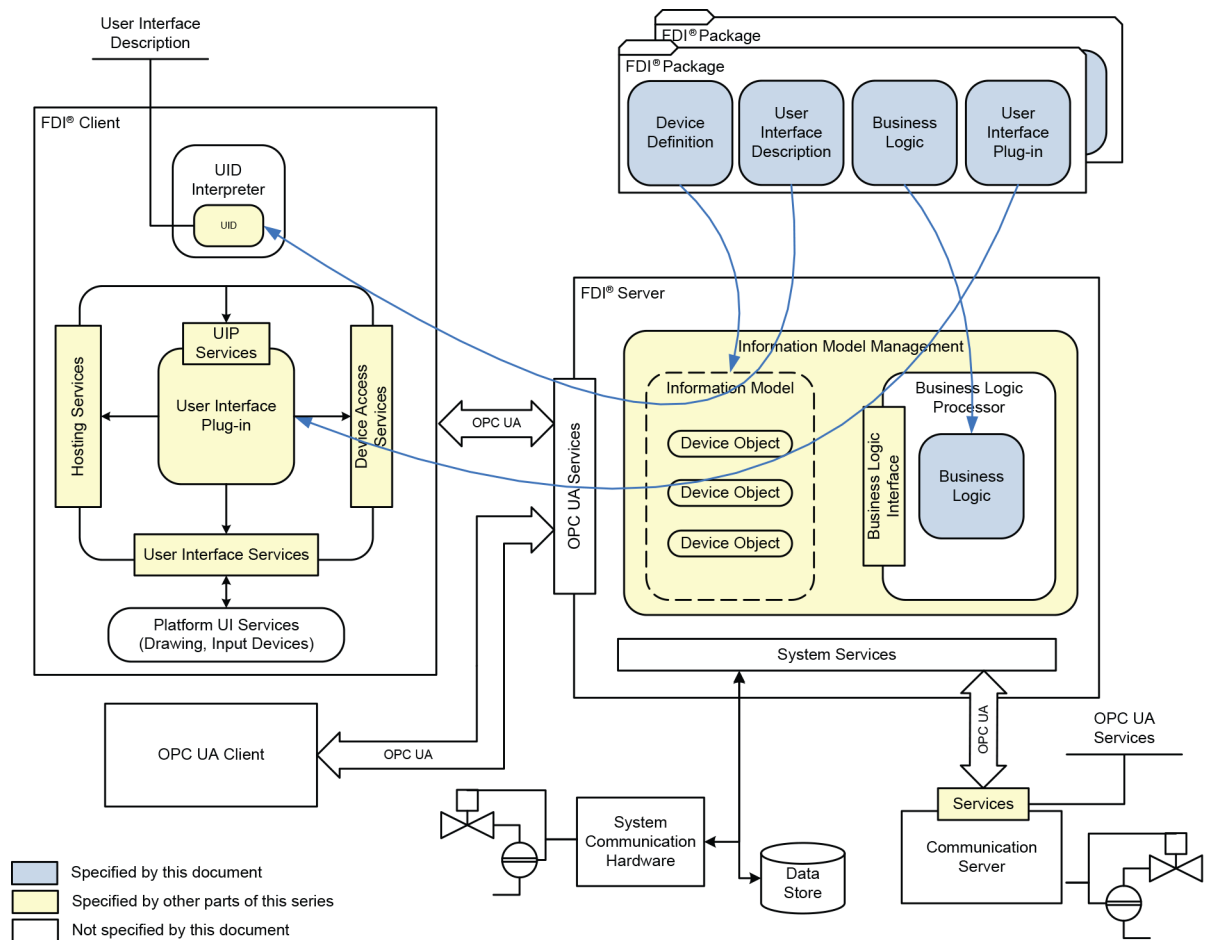


Figure 1 – FDI® architecture diagram

2 Normative references

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